

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JI HAENG LEE	11/20/2014
DONG SUN KIM	11/20/2014
SUNG WUK RYU	11/20/2014
RECEIVING PARTY DATA	
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City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	100-714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14524688
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ATTORNEY DOCKET NUMBER:	WIP.LGI.195
NAME OF SUBMITTER:	JEFF LLOYD
SIGNATURE:	/JEFF LLOYD/
DATE SIGNED:	11/24/2014
Total Attachments: 1 source=Exec-assgn#page1.tif	

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) Ji Haeng LEE (4) _____
- (2) Dong Sun KIM (5) _____
- (3) Sung Wuk RYU (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

LG INNOTEK CO., LTD.
Seoul Square, 416, Hangang-daero, Jung-gu
Seoul, 100-714 Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

PRINTED CIRCUIT BOARD AND MANUFACTURING METHOD THEREOF AND SEMICONDUCTOR PACKAGE USING THE SAME

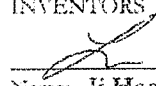
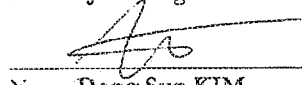
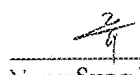
- (a) for which an application for United States Letters Patent was filed on October 27, 2014, and identified by United States Serial No. 14/524,688; or
- (b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and/or that claim priority thereto and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof and/or that claim priority thereto, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

AND the undersigned hereby grants the firm of KED & ASSOCIATES, LLP the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of any issuing authority, including the United States Patent and Trademark Office, for recordation of this document.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u></u> Name: Ji Haeng LEE	<u>11/20/2014</u>
2) <u></u> Name: Dong Sun KIM	<u>11.20.2014</u>
3) <u></u> Name: Sung Wuk RYU	<u>11.20.2014</u>
4) _____ Name:	_____
5) _____ Name:	_____
6) _____ Name:	_____

PATENT